



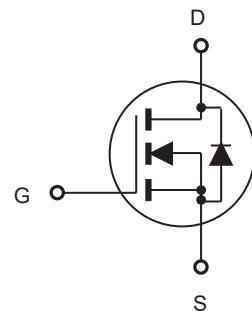
CEP04N7B/CEB04N7B CEF04N7B

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

Type	V _{DSS} @T _J max	R _{DS(ON)}	I _D	@V _{GS}
CEP04N7B	750V	3.2Ω	4A	10V
CEB04N7B	750V	3.2Ω	4A	10V
CEF04N7B	750V	3.2Ω	4A ^d	10V

- Super high dense cell design for extremely low R_{DS(ON)}.
- High power and current handing capability.
- Pb-free lead plating ; RoHS compliant.
- Halogen Free.



ABSOLUTE MAXIMUM RATINGS T_C = 25°C unless otherwise noted

Parameter	Symbol	Limit		Units
		TO-220/263	TO-220F	
Drain-Source Voltage	V _{DS}	700		V
Gate-Source Voltage	V _{GS}		±30	V
Drain Current-Continuous @ T _C = 25°C @ T _C = 100°C	I _D	4	4 ^d	A
		2.4	2.4 ^d	A
Drain Current-Pulsed ^a	I _{DM} ^e	16	16 ^d	A
Maximum Power Dissipation @ T _C = 25°C - Derate above 25°C	P _D	78	33	W
		0.62	0.26	W/°C
Single Pulsed Avalanche Energy ^g	E _{AS}		72.2	mJ
Single Pulsed Avalanche Current ^g	I _{AS}		3.8	A
Operating and Store Temperature Range	T _{J,T_{stg}}		-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Limit		Units
Thermal Resistance, Junction-to-Case	R _{θJC}	1.6	3.7	°C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	62.5	65	°C/W



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Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units	
Off Characteristics							
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$	700			V	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 700\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA	
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA	
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA	
On Characteristics ^b							
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_{\text{D}} = 250\mu\text{A}$	2		4	V	
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 2\text{A}$		2.7	3.2	Ω	
Gate input resistance	R_g	f=1MHz,open Drain		2.3		Ω	
Dynamic Characteristics ^c							
Input Capacitance	C_{iss}	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		615		pF	
Output Capacitance	C_{oss}			75		pF	
Reverse Transfer Capacitance	C_{rss}			15		pF	
Switching Characteristics ^c							
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 300\text{V}, I_{\text{D}} = 4\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 25\Omega$		28		ns	
Turn-On Rise Time	t_r			16		ns	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			39		ns	
Turn-Off Fall Time	t_f			19		ns	
Total Gate Charge	Q_g	$V_{\text{DS}} = 300\text{V}, I_{\text{D}} = 4\text{A}, V_{\text{GS}} = 10\text{V}$		10.4		nC	
Gate-Source Charge	Q_{gs}			2.7		nC	
Gate-Drain Charge	Q_{gd}			3.2		nC	
Drain-Source Diode Characteristics and Maximum Ratings							
Drain-Source Diode Forward Current	I_s ^f	$V_{\text{GS}} = 0\text{V}, I_s = 4\text{A}$			4	A	
Drain-Source Diode Forward Voltage ^b	V_{SD}				1.4	V	
Reverse Recovery Time	T_{rr}			400		ns	
Reverse Recovery Charge	Q_{rr}			2		uC	
Notes :							
a.Repetitive Rating : Pulse width limited by maximum junction temperature .							
b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$. Duty Cycle $\leq 2\%$.							
c.Guaranteed by design, not subject to production testing.							
d.Limited only by maximum temperature allowed .							
e.Pulse width limited by safe operating area .							
f.Full package $I_{\text{S}(\text{max})} = 2.3\text{A}$.							
g. $L = 10\text{mH}$, $I_{\text{AS}} = 3.8\text{A}$, $V_{\text{DD}} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$.							



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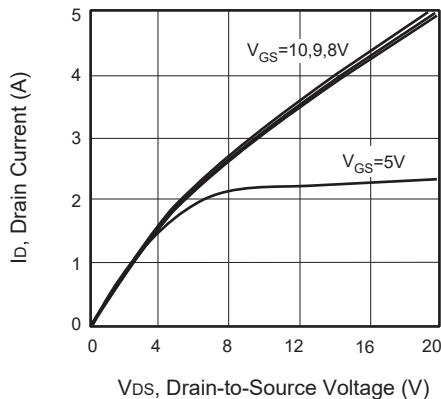


Figure 1. Output Characteristics

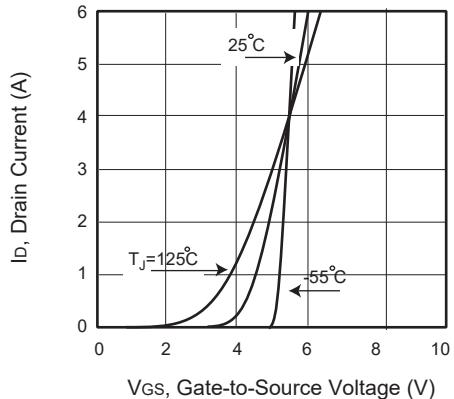


Figure 2. Transfer Characteristics

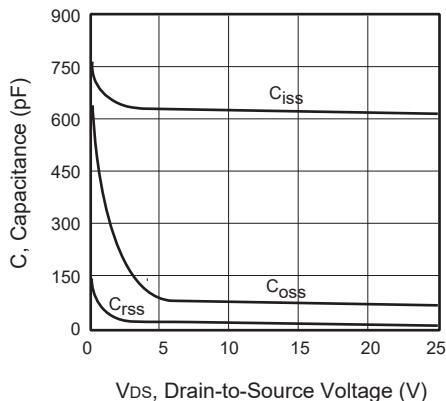


Figure 3. Capacitance

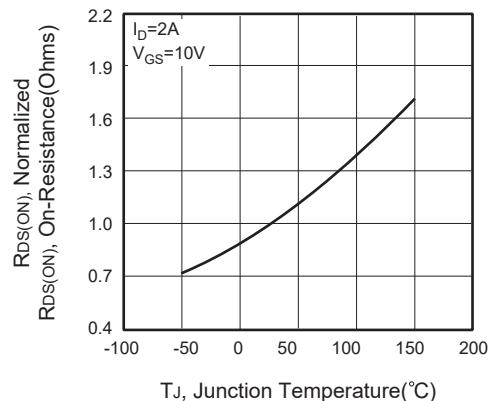


Figure 4. On-Resistance Variation with Temperature

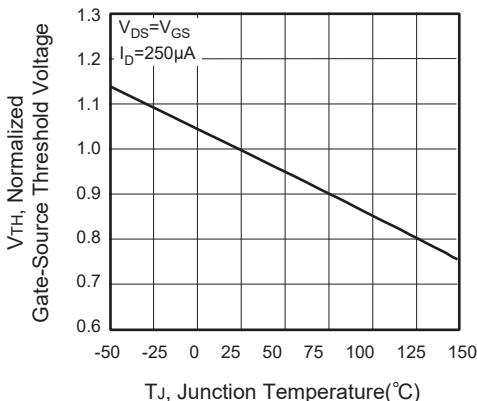


Figure 5. Gate Threshold Variation with Temperature

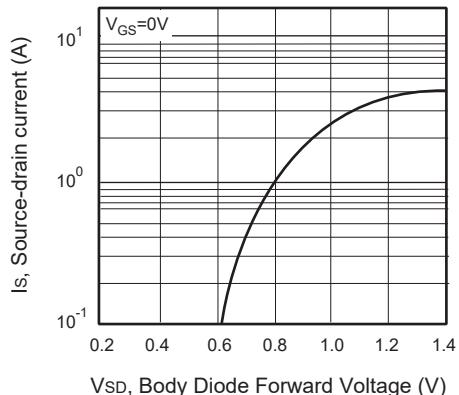


Figure 6. Body Diode Forward Voltage Variation with Source Current



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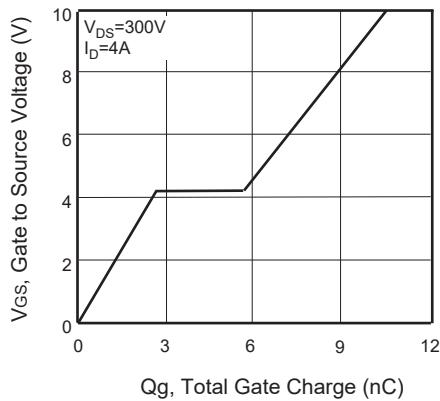


Figure 7. Gate Charge

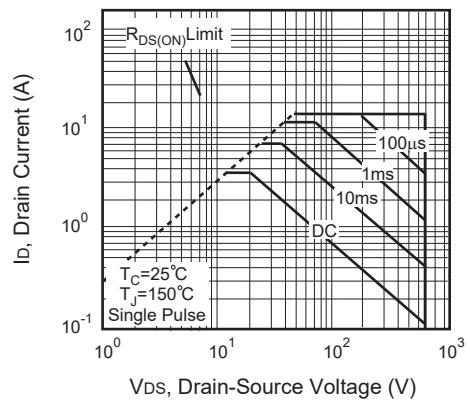


Figure 8. Maximum Safe
Operating Area

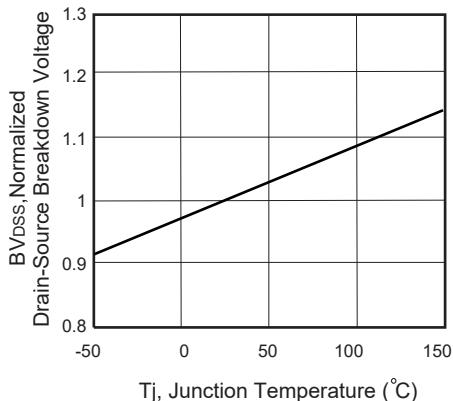


Figure 9. Breakdown Voltage Variation
VS Temperature

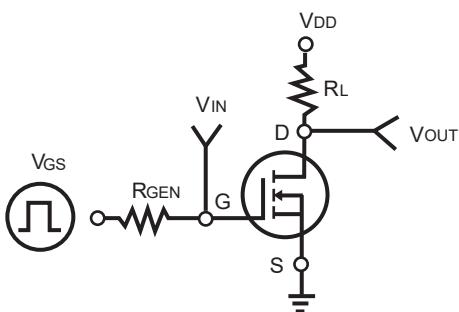


Figure 10. Switching Test Circuit

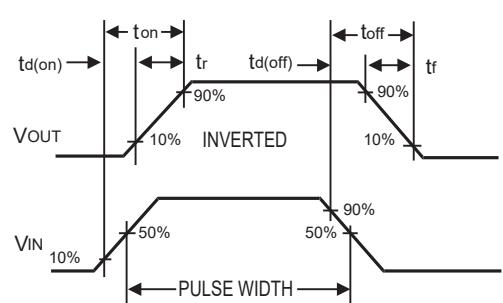


Figure 11. Switching Waveforms



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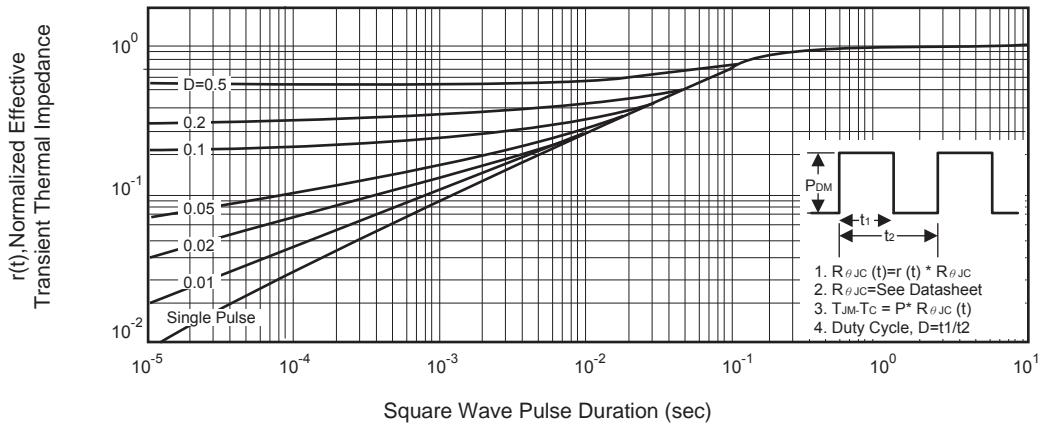


Figure 12. Normalized Thermal Transient Impedance Curve